

Electronic Acknowledgement Receipt

EFS ID:	2742044
Application Number:	10681747
International Application Number:	
Confirmation Number:	8137
Title of Invention:	SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING INVERTED SECOND PACKAGE STACKED OVER DIE-UP FLIP-CHIP BALL GRID ARRAY (BGA) PACKAGE
First Named Inventor/Applicant Name:	Marcos Karnezos
Customer Number:	22470
Filer:	Mikio Ishimaru/Victoria Rocha
Filer Authorized By:	Mikio Ishimaru
Attorney Docket Number:	CPAC 1029-6
Receipt Date:	18-JAN-2008
Filing Date:	08-OCT-2003
Time Stamp:	21:35:01
Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /.zip	Pages (if appl.)
1	Miscellaneous Incoming Letter	27-409-5CP_Transmittal_Change_POA_Address.pdf	49010 836edb8261076083d9f5bee4e97f6e6e d87171b4	no	1

Warnings:

Information:

2	Power of Attorney	27-409-5CP_ChipPAC_Inc_signed_POA.pdf	69127 024c95bea540a6d6b860bb9eecc64f8b cc1a6e08	no	1
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Warnings:

Information:

3	Assignee showing of ownership per 37 CFR 3.73(b).	27-409-5CP_STATEMENT_under_3-73b.pdf	140763 518b4f09fffffe5c83854613bfedd20d36 d4ac2	no	2
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Warnings:

Information:

4	Change of Address	27-409-5CP_Fee_Address_Indication_Form.pdf	142008 1427c70d471670d4cb037f6147c21aad7 37d99da	no	2
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Warnings:

Information:

Total Files Size (in bytes):	400908
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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.